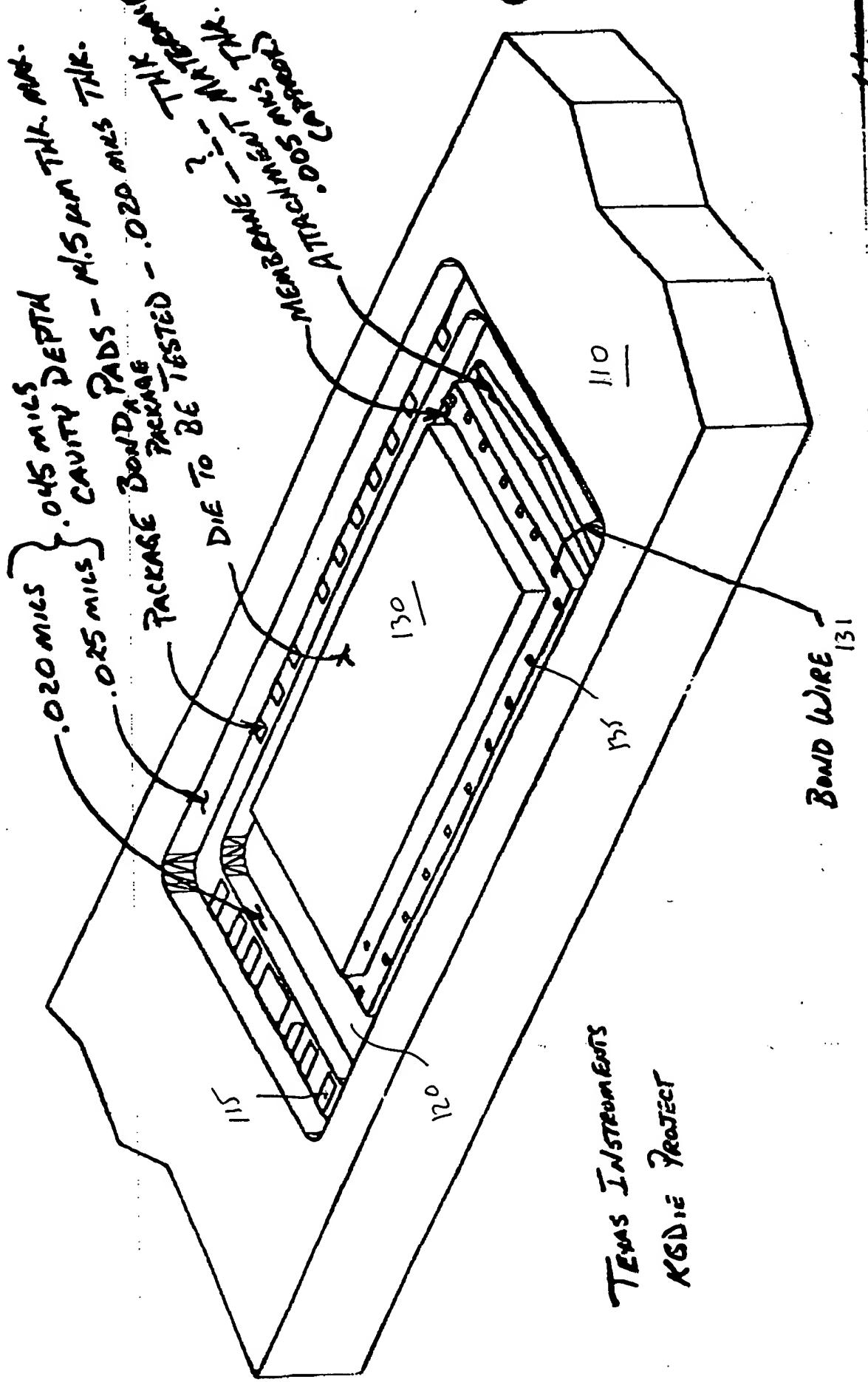


② Figure 2 Flip Config - ~~05-160317~~ - ~~05-160317~~ Package, Exploded View

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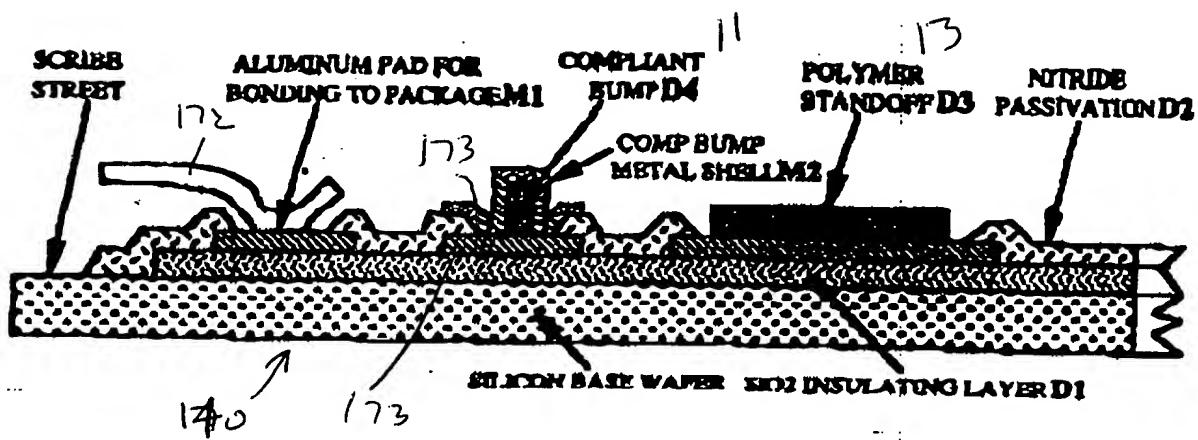
② 12

3

15

①

Figure 3 Compliant bump with polymer stand off
on K60/FL silicon membrane, Cross Section.



(8)

(13)

Figure 4 Flip configuration of K60 IC Package, Cross Section

TEXAS INSTRUMENTS

MILITARY PRODUCTS DIVISION

KGD/IE FLIP CONFIGURATION

PRODUCTION BY USE OF EXISTING BURN-IN AND TEST TOOLING

- MULTI BOND LAYER PACKAGE
- SINGLE ALIGNMENT PROCESS
- REUSABLE
- SAME COST AS OF ORIGINAL CONFIGURATION

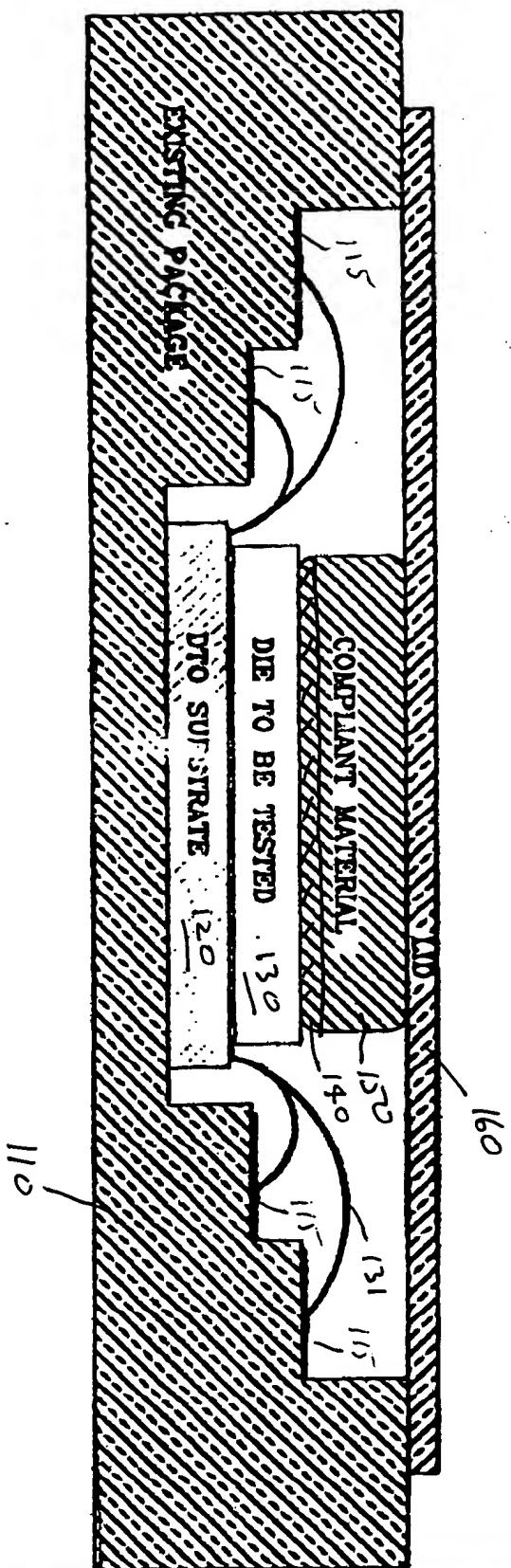


FIGURE 1: Generic KGD/IE Implementation, Exploded View